



# Very Large Scale Integration II - VLSI II

## Memory Structures

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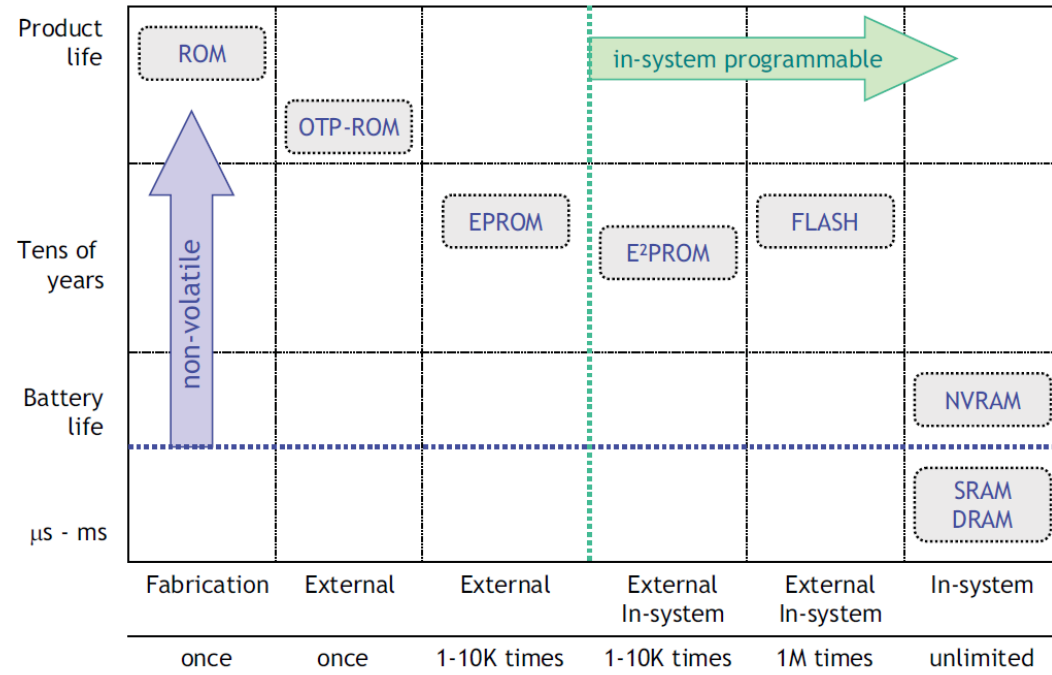
## Memory Structures

- Traditional ROM/RAM distinctions:
  - ROM read only, data can be stored without power
  - RAM read and write, data can not be stored without power
- Traditional distinctions are blurred:
  - Advanced ROMs can be written e.g., EEPROM, FLASH
  - Advanced RAMs can hold bits without power e.g., NVRAM



## Memory Structures

- There is trade-off between the **Write ability** and **storage permanence (life)**
- Write ability: Manner and speed a memory can be written.
- Storage permanence : Ability to hold stored bits once written





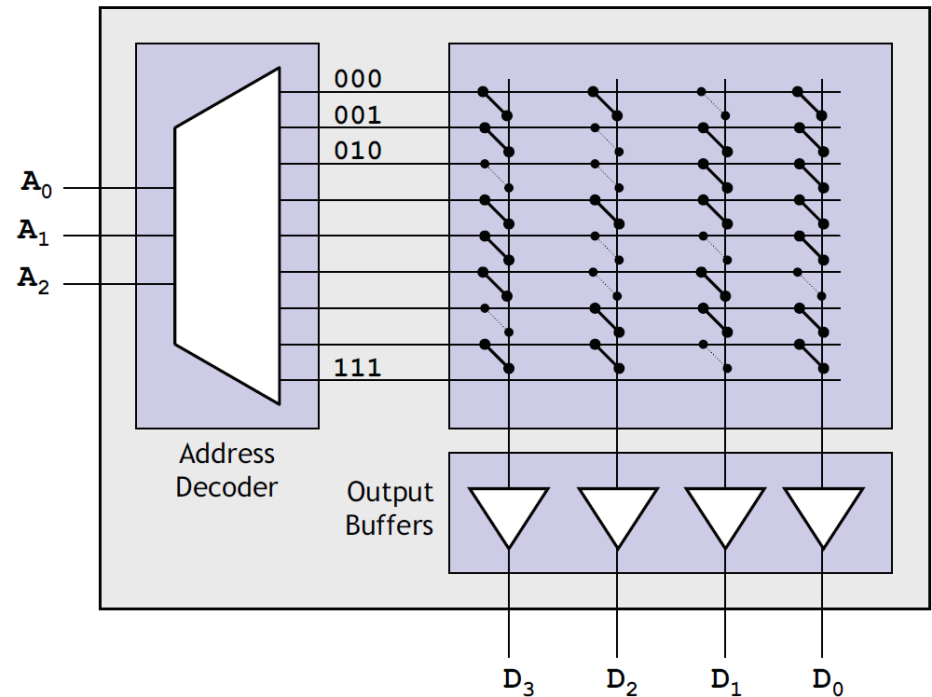
## Memory Structures

- Ranges of write ability:
  - High end [RAM]
  - Middle range [EEPROM]
  - Lower range [EPROM, OTP ROM]
  - Low end [Mask-programmed ROM]
- Range of storage permanence
  - High end [mask-programmed ROM]
  - Middle range [NVRAM]
  - Lower range [SRAM]
  - Low end [DRAM]



## Read-Only Memory (ROM)

- Read-Only Memories are nonvolatile
- Read-only memory is useful for storing software that is rarely changed.







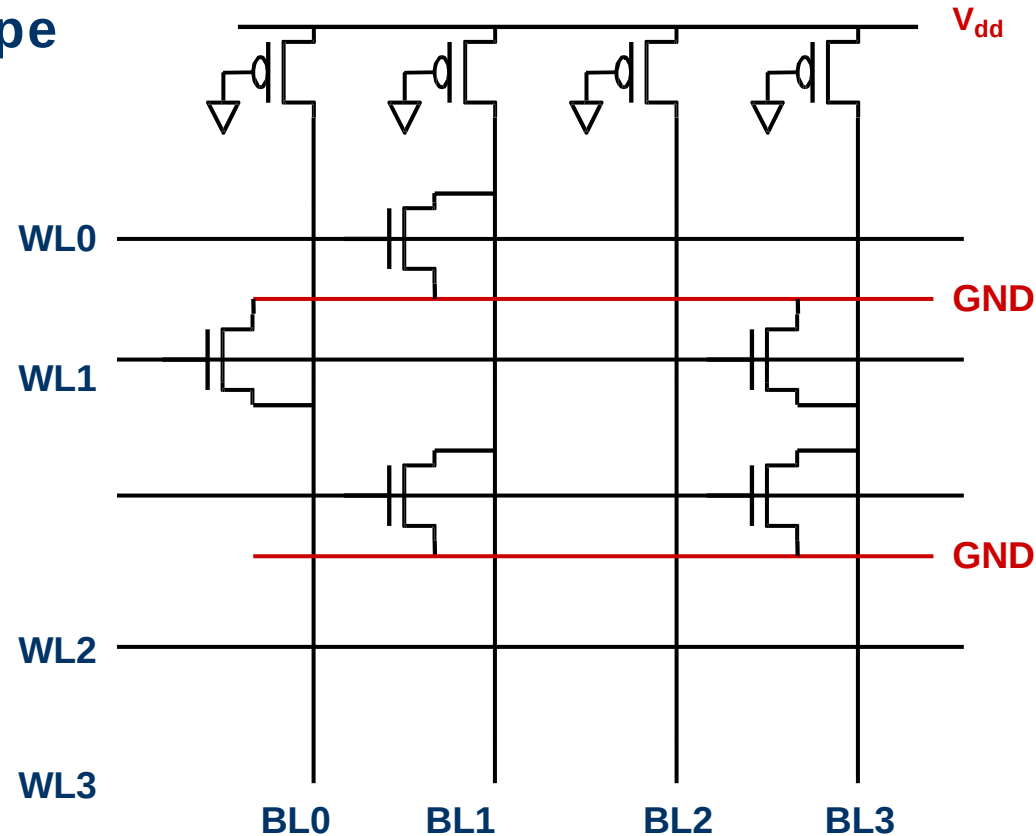
## Mask-programmed ROM

- Mask-programmed ROM
  - Programmed only once by manufacturer at fabrication(mask) process.
  - Mask-programmed ROMs use one transistor per bit (Presence or absence determines 1 or 0).
  - Highest storage permanence (life of product).
  - Cheaper but design errors are costly.
  - Many microprocessors have Mask-ROM to store their microcode. Bootloaders and firmware can also be stored in Mask-ROMs.



## Mask-programmed ROM

4x4 NOR-type  
ROM





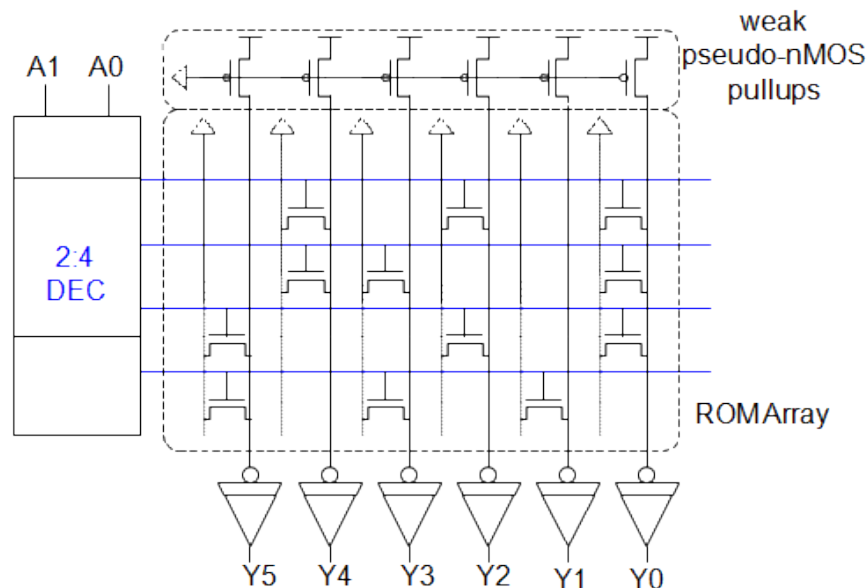
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## ROM Example

- 4-word x 6-bit ROM
- Represented with dot diagram
- Dots indicate 1's in ROM

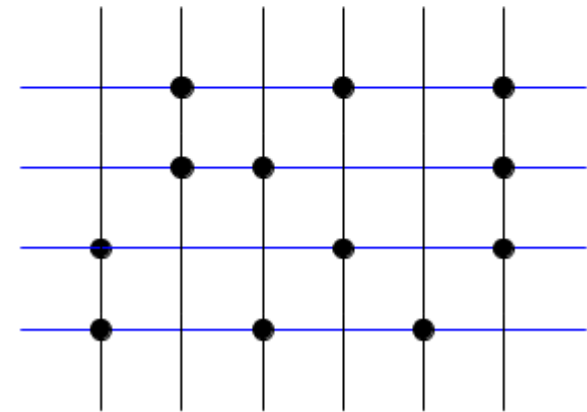


Word 0: 010101

Word 1: 011001

Word 2: 100101

Word 3: 101010



Looks like 6 4-input pseudo-nMOS NORs



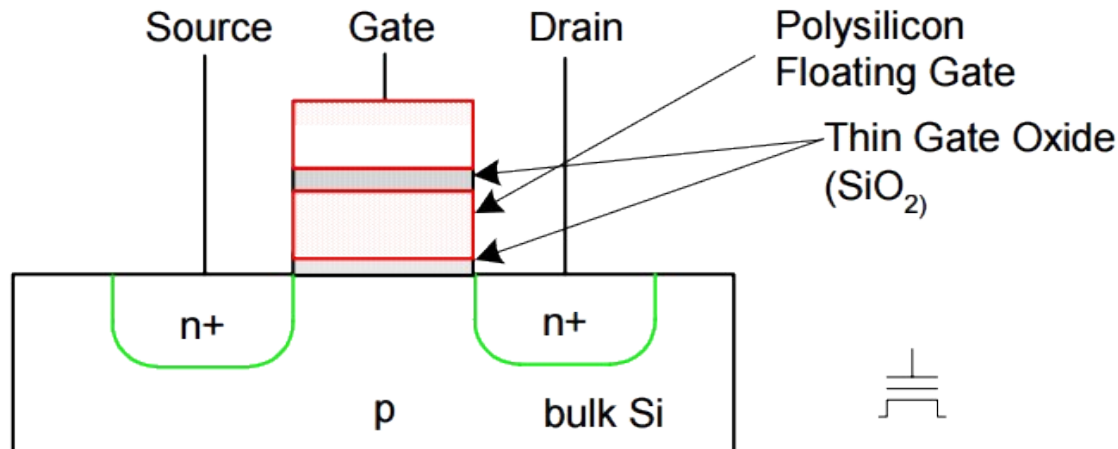
## Field Programmable ROMs

- Erasable programmable ROM (EPROM)
  - Programmable component is a MOS transistor, and transistor has “floating” gate.
  - Can be erased and reprogrammed thousands of times.
  - Reduced storage permanence, lasts about 10 years.
  - Not **in-system** programmable, historical.
- E2PROM
  - Programmed and erased electronically, **in-system** programmable.
  - Can be erased and programmed tens of thousands of times.
  - Storage permanence about 10 years.



## FLASH

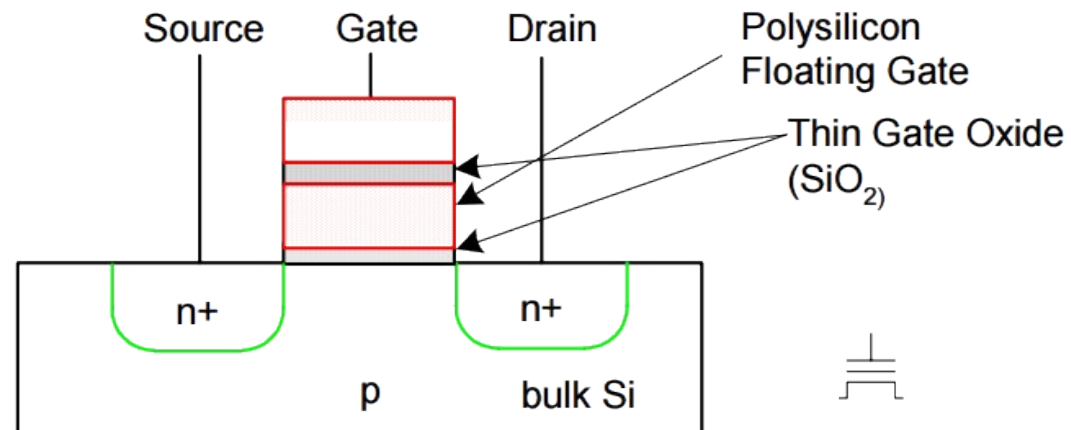
- Extension of EEPROM
  - Same floating gate principle.
  - Fast erase, better write ability.





# FLASH

- The adding of a load of electrons at the isolated gate is "programming" of the transistor while electrons removal is "deleting".
- Has electron load  
 $V_T$  increases  
(open switch)
- Opposite case  $V_T$  decreases  
(closed switch)

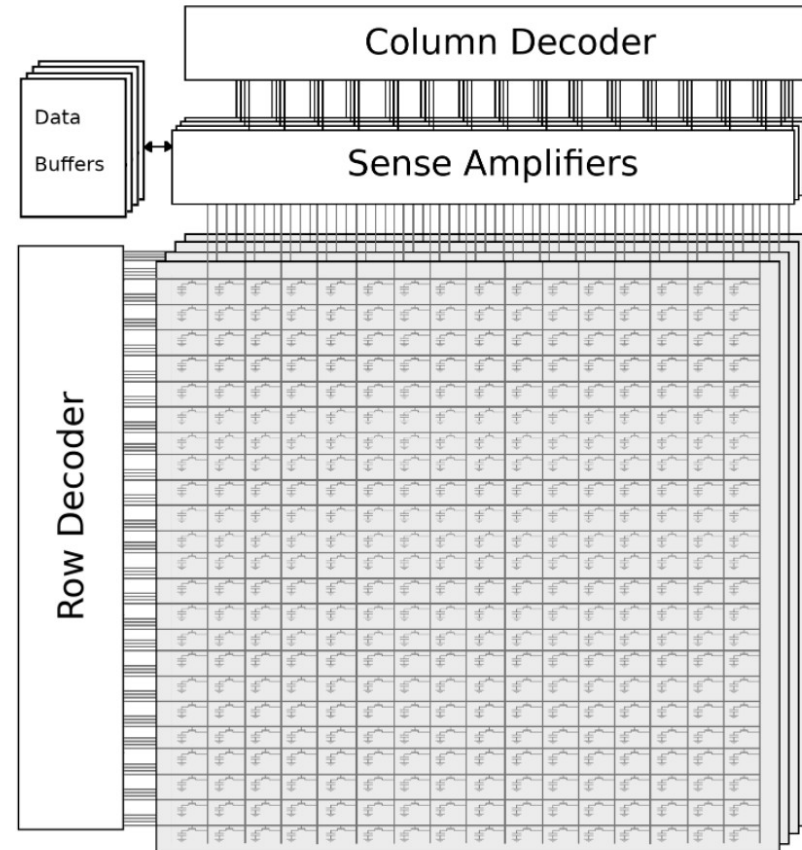






## Random-Access Memory (RAM)

- Typically volatile memory
- Typically used to store working data and machine code.









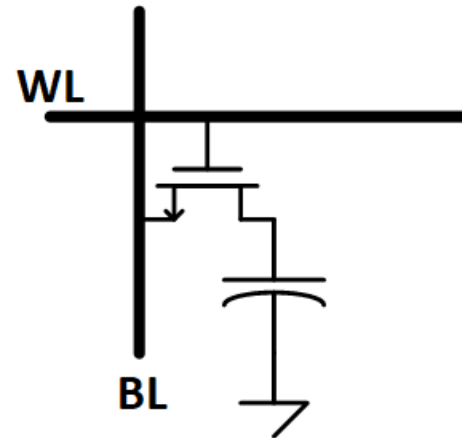
## SRAM

- Not area efficient (at least 6 transistor for 1-bit data)  $\rightarrow$
- Expensive due to area inefficiency  $\rightarrow$
- No special semiconductor process (like in the FLASH)  $\wedge$
- Fast  $\wedge$
- Low power consumption  $\wedge$
- Easy to communicate  $\wedge$
- Used in
  - Embedded systems
  - CPU On-Chip Memory, Cache
  - FPGAs



## Dynamic RAM (DRAM)

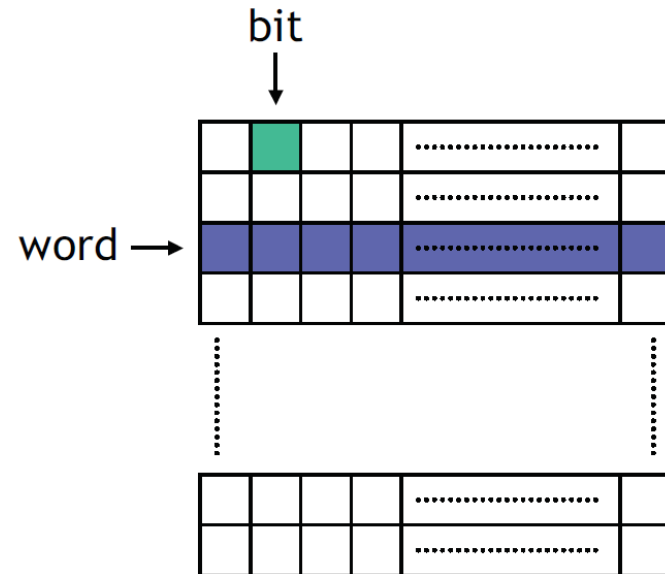
- DRAM uses a MOS transistor and a capacitor to store a bit
- More compact than SRAM
- "Refresh" required due to capacitor leak dynamic memory cells must be repeatedly read and restored.
- Slower than SRAM
- Cheaper





## Basic Concepts

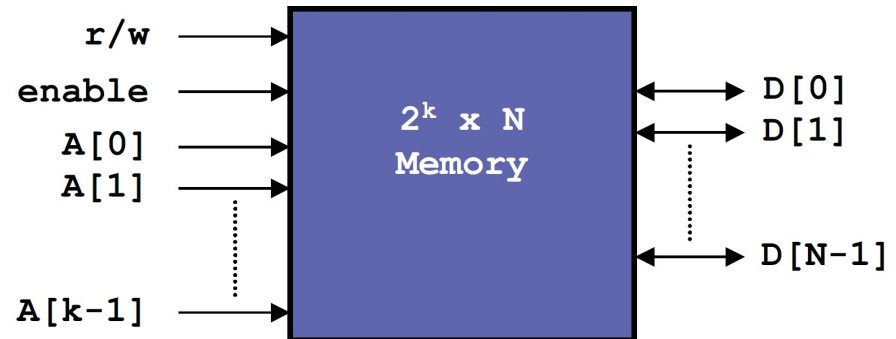
- Memories are organized in words (groups of bits  $2^k$ )
- An  $M \times N$  memory
  - $M=2^k$  words
  - $N$  bits per word
- E.g.: 4096 x 8 memory:
  - $4,096 \times 8 = 32,768$  bits
  - $4,096 = 2^{12}$
  - 12 address input signals
  - 8 input/output data signals (buses)





## Basic Concepts

- Memory access signals
  - r/w Selects read or write
  - **enable** Read or write only when asserted
- Memory address/data
  - $A[0..k-1]$  Address
  - $D[0..N-1]$  Data





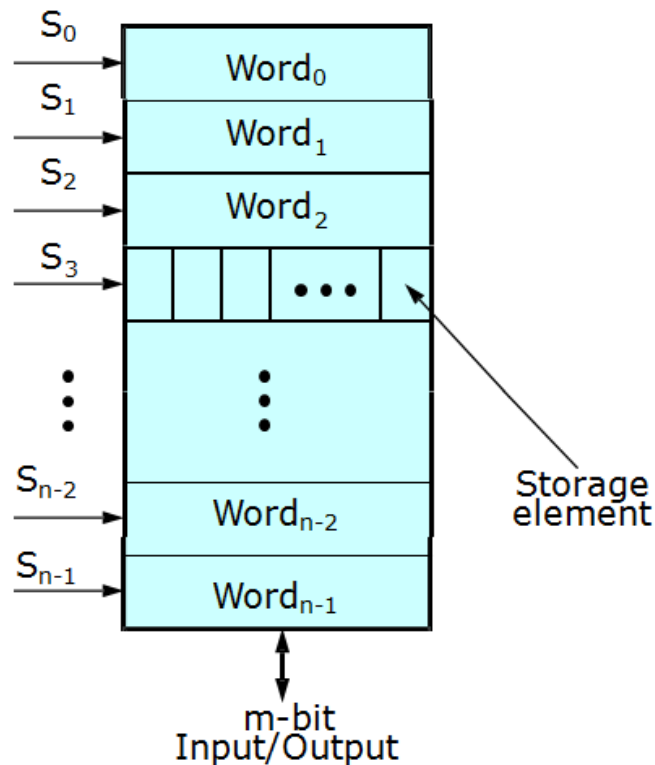


## Memory Organization

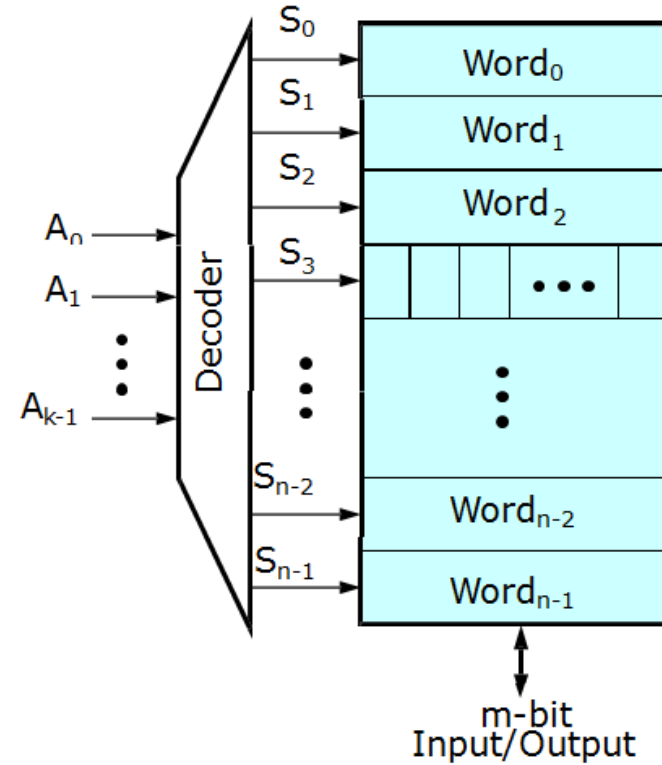
- **Random Access:** Each memory location has a unique address, data can be accessed in any order.
- **Sequential Access:** Data can be accessed in a sequential order.
- **Content Addressable:** (Associative memory) compares the input with all the stored data



# 1-D Memory Architecture



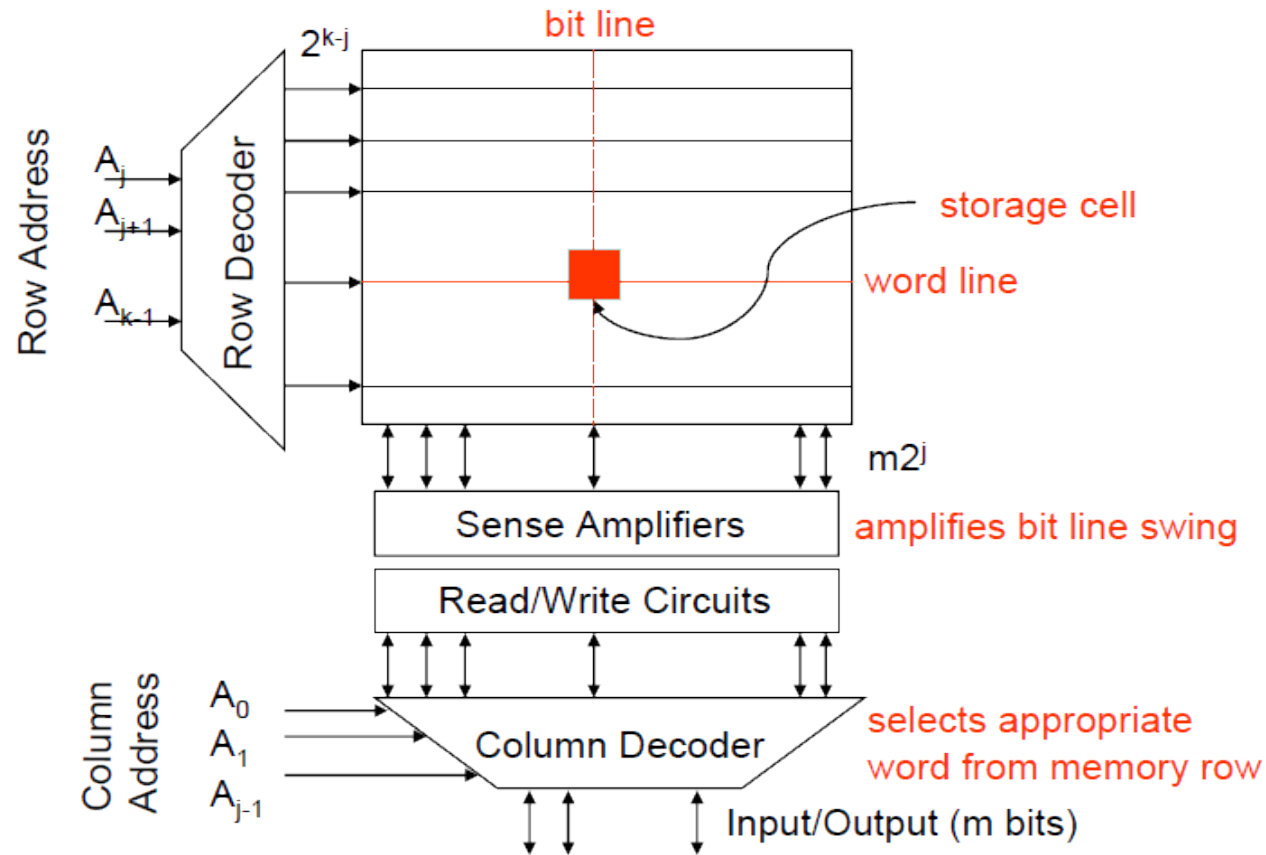
$n$  select signals:  $S_0-S_{n-1}$



$n$  select signals are reduced to  $k$  address signals:  $A_0-A_{k-1}$

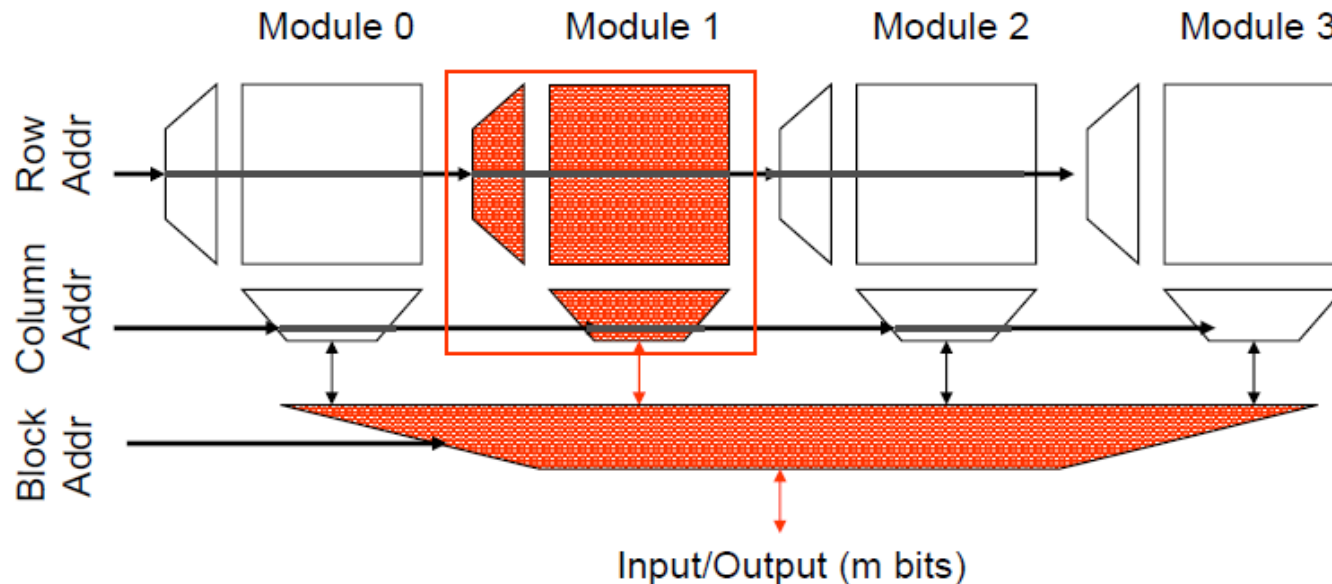


## 2-D Memory Architecture





## 3-D Memory Architecture



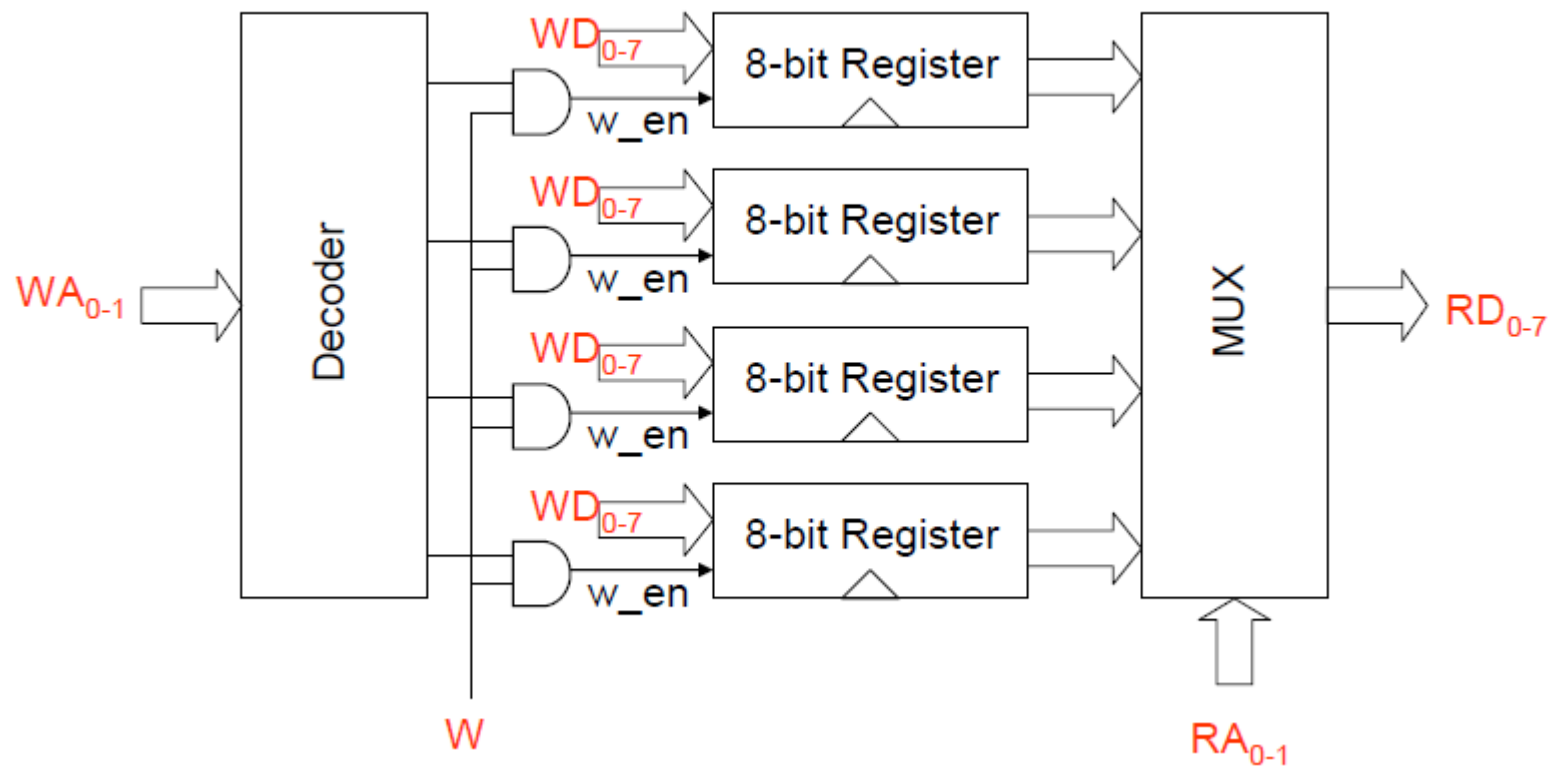
### Advantages:

1. Shorter word/bit lines (**reduced delay**)
2. Enable only one module at a time (**reduced power**)





## FF Based Memories







## References

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